

Altera Device Package Information

04R-00240-1.0

484-Pin FineLine Ball-Grid Array (FBGA) - Flip Chip - Dual-Piece Lid - A:3.20

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

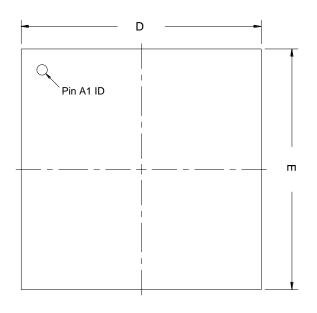
Package Information		
Description	Specification	
Ordering Code Reference	F	
Package Acronym	FBGA	
Substrate Material	ВТ	
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)	
JEDEC Outline Reference	MO-034 Variation: AAJ-1	
Lead Coplanarity	0.008 inch (0.20 mm)	
Weight	6.0 g (Typ.)	
Moisture Sensitivity Level	Printed on moisture barrier bag	

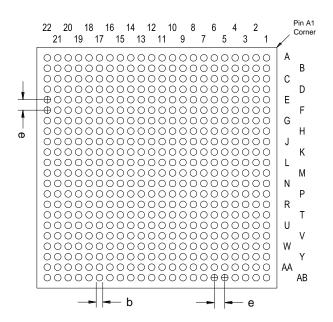
	imension Table Millimeters			
Symbol	Min.	Nom.	Max.	
Α	2.90	3.05	3.20	
A1	0.40	0.50 2.55	0.60 2.80	
A2	2.30			
А3	1.40	1.50	1.60	
D	23.00 BSC			
E	23.00 BSC			
b	0.50	0.60	0.70	
е		1.00 BSC		

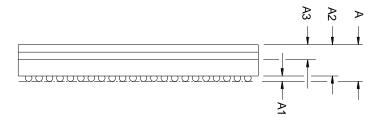
Package Outline

TOP VIEW

BOTTOM VIEW







Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
June 2011	1.0	Initial release



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